



SPECIFICATION



PH128128T041-LAA07

1.44" - 128x128 - MPU/CPU

Version: 1.2

Date: 16.04.2018

Note: This specification is subject to change without prior notice



History of Version

Date	Ver.	Edi.	Description	Page	Design by
2018/2/26	01	001	New Drawing	-	夏子豪
2018/4/16	01	002	New Sample	-	夏子豪

Total: 29 Pages



Contents

1. SPECIFICATIONS

- 1.1 Features
- 1.2 Mechanical Specifications
- 1.3 Absolute Maximum Ratings
- 1.4 DC Electrical Characteristics
- 1.5 Optical Characteristics
- 1.6 Backlight Characteristics

2. MODULE STRUCTURE

- 2.1 Counter Drawing
 - 2.2.1 Refer Initial Code
- 2.2 Interface Pin Description
- 2.3 Timing Characteristics

3. QUALITY ASSURANCE SYSTEM

- 3.1 Quality Assurance Flow Chart
- 3.2 Inspection Specification

4. RELIABILITY TEST

4.1 Reliability Test Condition

5. PRECAUTION RELATING PRODUCT HANDLING

- 5.1 Safety
- 5.2 Handling
- 5.3 Storage
- 5.4 Terms of Warranty

Appendix: 1. LCM Drawing

2. LCM Packaging



1. SPECIFICATIONS

1.1 Features

Main LCD Panel

- Main LOD I and					
Item	Standard Value				
Display Type	128(R · G · B) * 128 Dots				
LCD Type	Normally white TN, Transmissive type				
Screen size(inch)	1.44 inch				
Viewing Direction	12 O'clock				
Color configuration	R.G.B. vertical stripe				
Backlight	White LED				
Interface	8 bit Parallel Interface				
Other(controller / driver IC)	Sitronix: ST7735S				
	THIS PRODUCT CONFORMS THE ROHS OF PTC				
ROHS	Detail information please refer web side :				
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/				

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	31.1 (W) * 36.9 (L) * 2.85 (H)	mm

TFT LCD Panel

Item	Standard Value	Unit
Viewing Area	26.498 (W) *27.496 (L)	mm
Active Area	25.498 (W) * 26.496 (L)	mm

Note: For detailed information please refer to LCM drawing.



1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit
Supply Voltage	VDD	-	-0.3	+4.8	V
Supply Voltage(Logic)	VDDI	-	-0.3	+4.6	V
Driver supply voltage	VGH-VGL	-	-0.3	+30.0	V
Logic input voltage range	VIN	-	-0.3	VDDI+0.3	V
Logic output voltage range	VO	-	-0.3	VDDI+0.3	V
Operating Temperature	TOP	-	-20	+70	°C
Storage Temperature	TST	-	-30	+80	°C
Storage Humidity	HD	Ta ≦ 60 °C	-	90	%RH

1.4 DC Electrical Characteristics

Module GND = 0V, Ta = 25°C

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
System voltage	VDD	-	2.7	3.0	3.3	V
Interface operation voltage	VDDI	-	1.65	1.8	3.7	V
Logic-high input voltage	VIH	-	0.7VDDI	-	VDDI	V
Logic-low input voltage	VIL	-	VSS	-	0.3VDDI	V
Logic-high output voltage	VOH	IOH=-1.0mA	0.8VDDI	-	VDDI	V
Logic-low output voltage	VOL	IOL=+1.0mA	VSS	-	0.2VDDI	V
Supply Current	IDD	VDD=3.0V	-	1.6	2.5	mA



1.5 Optical Characteristics

TFT LCD Panel

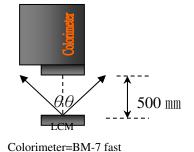
VDD=3.0V, Ta=25°C

Item		Symbol	Condition	Min.	Тур.	Max.	unit	-
Response tin	ne	Tr+ Tf	-	-	-	-	ms	Note2
	Тор	θΥ+		-	15	-		
Viowing angle	Bottom	θΥ-	CD>(10)	-	45	-	Dog	Note4
Viewing angle	Left	θΧ-	CR≥(10)	1	45	ı	Deg.	NOIE4
	Right	θX+	ı	45	ı			
Contrast rati	0	CR	-	150	200	-	-	Note3
	\	Х		0.25	0.30	0.35		Note1
	White	Υ	IF=20mA	0.26	0.31	0.36	_	
Color of CIE	Red	Х		0.59	0.64	0.69		
Color of CIE Coordinate		Υ		0.29	0.34	0.39		
(With B/L)	Green	Х	11 –2011/7	0.27	0.32	0.37		Note
,		Υ		0.52	0.57	0.62		
	Blue	X		0.09	0.14	0.19		
	Diue	Υ		0.05	0.10	0.15		
Average Brightness Pattern=white display (With B/L)		IV	IF=20mA	200	310	-	cd/m2	Note1
Uniformity (With B/L)		∆B	IF=20mA	80	-	-	%	Note1

Note1:

- 1 : $\triangle B= B(min) / B(max) \times 100\%$.
- 2: Measurement Condition for Optical Characteristics:
 - a : Environment: 25°C±5°C / 60±20%R.H, no wind, dark room below 10 Lux at typical lamp current and typical operating frequency.
 - b : Measurement Distance: 500 ± 50 mm, $(\theta = 0^{\circ})$.
 - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
 - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%.



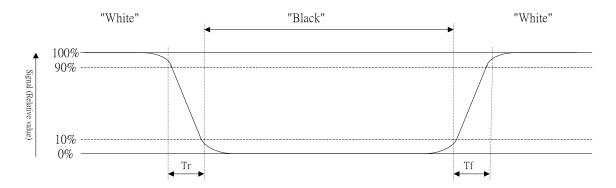




Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:



Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

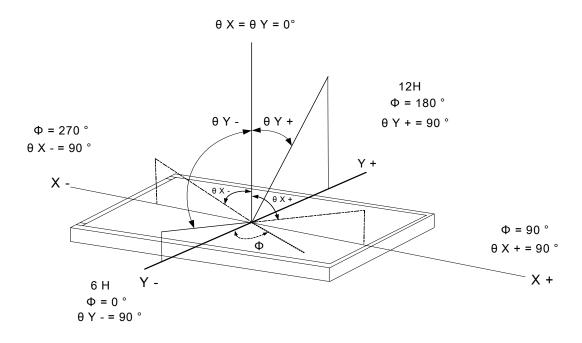
Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle:

Refer to figure as below:





1.6 Backlight Characteristics

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°ℂ	-	30	mA
Reverse Voltage	VR	Ta =25°ℂ	-	5.0	V
Power Dissipation	PD	Ta =25°ℂ	-	90	mW

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF= 20mA	2.8	3.2	3.6	V
Average Brightness	IV	IF= 20mA	4000	5000	-	cd/m ²
Color of CIE Coordinate	Х	IF= 20mA	0.27	0.30	0.33	
Color of CIE Coordinate	Y	IF- ZUIIIA	0.27	0.30	0.33	-
Color	White					

Circuit diagram



Other Description

Item	Conditions	Description
Life Time	Ta =25°ℂ	20000 hrs
Lile Time	IF= 20mA	20000 1115

PH128128T041-LAA07 Page8 SAMPLE Ver.01 SPEC Edi.002



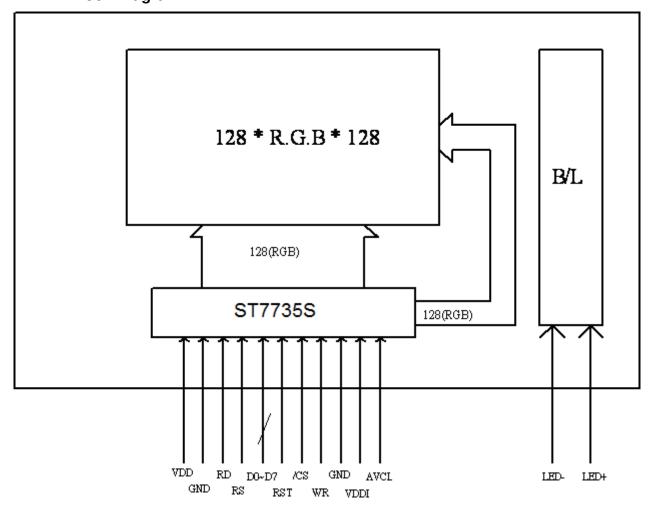
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram



PH128128T041-LAA07 Page9 SAMPLE Ver.01 SPEC Edi.002



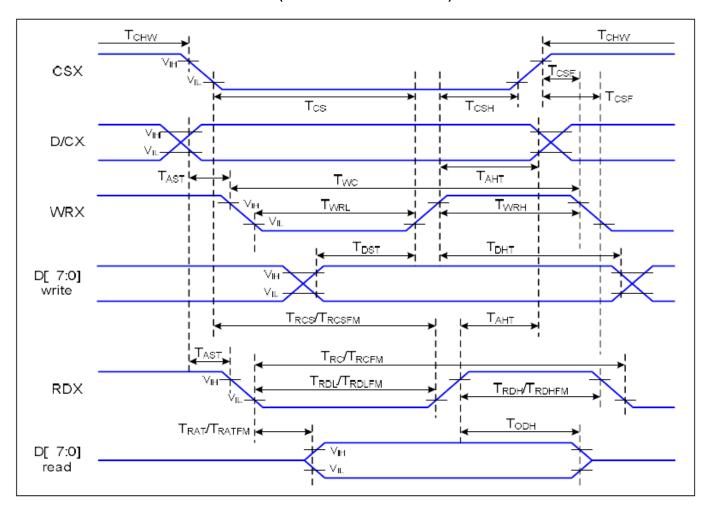
2.2 Interface Pin Description

Pin NO	Symbol	Function
1	LED+	Backlight LED anode input pin.
2	LED-	Backlight LED cathode input pin.
3	GND	System ground
4	VDD	Dever example for analog digital exators and becater circuit
5	VDD	Power supply for analog, digital system and booster circuit.
6	RD	Read enable in 8080 MCU parallel interface.
7	RS	Display data/command selection pin in MCU interface. RS ='1': display data or parameter. RS ='0': command data.
8	D1	
9	D3	DI7:01 are used as MOLL parallel interface data has
10	D5	D[7:0] are used as MCU parallel interface data bus.
11	D7	
12	RST	This signal will reset the device and it must be applied to properly initialize the chip. Signal is active low.
13	/CS	Chip selection pin, Low enable
14	D6	
15	D4	D[7:0] are used as MCLL parallel interface data bus
16	D2	D[7:0] are used as MCU parallel interface data bus.
17	D0	
18	WR	Write enable in MCU parallel interface.
19	GND	System ground
20	GND	System ground
21	VDDI	Power supply for I/O system.
22	AVCL	A power supply pin for generating GVCL.Connect a capacitor for stabilization.



2.3 Timing Characteristics

Parallel interface characteristics: 8-bit bus (8080 series MCU interface)



Parallel Interface Timing Characteristics (8080 Ceries MCU Interface)



Ta=25 °C, VDDI=1.65~3.7V, VDD=2.5~4.8V

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	TAST Address Setup Ttime		0		ns	
DIOX	TAHT	Address Hold Time (Write/Read)	10		ns	-
	TCHW	Chip Select "H" Pulse Width	0		ns	
	TCS	Chip Select Setup Time (Write)	15		ns	
csx	TRCS	Chip Select Setup Time (Read ID)	45		ns	
03/	TRCSFM	Chip Select Setup time (Read FM)	355		ns	-
	TCSF	Chip Select Wait Time (Write/Read)	10		ns	
	TCSH	Chip Select Hold Time	10		ns	
	TWC	Write Cycle	66		ns	
WRX	TWRH	Control Pulse "H" Duration	15		ns	
	TWRL	Control Pulse "L" Duration	15		ns	
	TRC	Read Cycle (ID)	160		ns	
RDX (ID)	TRDH	Control Pulse "H" Duration (ID)	90		ns	When Read ID Data
	TRDL	Control Pulse "L" Duration (ID)	45		ns	

RDX	TRCFM	Read Cycle (FM)	450		ns	When Read from
(FM)	TRDHFM	Control Pulse "H" Duration (FM)	90		ns	Frame Memory
(1 IVI)	TRDLFM	Control Pulse "L" Duration (FM)	355		ns	Traine Memory
D[7:0]	TDST	Data Setup Time	10		ns	
	TDHT	Data Hold Time	10		ns	
	TRAT	Read Access Time (ID)		40	ns	For CL=30pF
	TRATFM	Read Access Time (FM)		340	ns	
	TODH	Output Disable Time	20	80	ns	

8080 Parallel Interface Characteristics



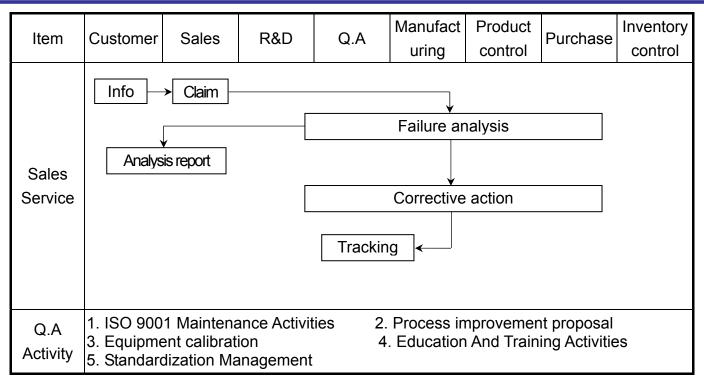
Out

3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart Manufactur Product Inventory Customer Item R&D Sales Q.A Purchase ing control control Info Survey **Project** evaluation Request Inquiry Marketing & Project Validation Design OK Quote Contract Design check Sample test Sample NG Approval Verification NG **V** OK Sample approval OK run & Reliability test Pilot Pilot NG Run Verification **V** OK & Specification preparation Mass Product Mass production OK NG Inspection Ship Shipment

Ship out







3.2. Inspection Specification

♦Scope : The document shall be applied to TFT-LCD Module for less than 3, 5" (Ver.B01).

◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

◆Equipment: Gauge、MIL-STD、Powertip Tester、Sample

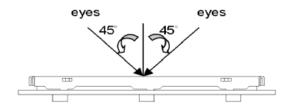
◆Defect Level: Major Defect AQL: 0,4; Minor Defect AQL: 1,5

◆OUT Going Defect Level: Sampling.

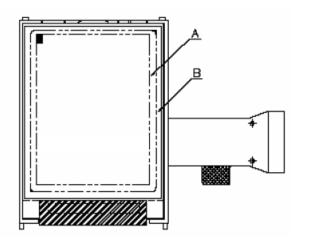
◆Standard of the product appearance test:

a. Manner of appearance test:

- (1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.
- (2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area : viewing area

B area: Outside of viewing area

(4). Standard of inspection : (Unit : mm)

PH128128T041-LAA07 Page15 SAMPLE Ver.01 SPEC Edi.002



lacktriangle Specification For TFT-LCD Module Less Than 3. 5":

NO	Item			Criteri	on	Level	
		1. 1The part number is inconsistent with work order of production.					
01	Product condition	1. 2 Mixed product types.					
		1. 3 As	sembled	in inverse direction.		Major	
02	Quantity	2. 1The quantity is inconsistent with work order of production.			. Major		
03	Outline dimension		3. 1 Product dimension and structure must conform to structure diagram.			ure Major	
		4. 1 Mi	issing line	e character and icon	1.	Major	
	Electrical Testing	4. 2 No function or no display.					
04		4. 3 Display malfunction.					
		4. 4 LCD viewing angle defect.				Major	
		4. 5 Cu	irrent coi	nsumption exceeds p	product specifications.	Major	
	Dot defect			Item	Acceptance (Q'ty)		
				Bright Dot	≦ 2		
	200 401000		Dot	Dark Dot	≦ 3		
05	(Bright dot \		Defect	Joint Dot	≦ 2	Minor	
UO	Dark dot)			Total	≦ 3	Willior	
	On -display	1		spection	pattern : full white	, full black , Red , Green	and
				blue screei			
					ect area >1/2 dot.		
		5. 3 Th	e distanc	e between two dot d	neiect ≤9 mm.		



◆Specification For TFT-LCD Module Less Than 3.5":

NO	Item		Cr	iterion	l		Level
		6. 1 Round type (Non-display or display):					
		Di	Dimension Acceptance (Q'ty)				
		(dia	meter ∶Φ)		A area	B area	
	Black or white dot \ scratch \	$\Phi \le 0.15$			Ignore		
	contamination	0.15	$<\Phi \le 0.20$		2		
	Round type	0.20	< Φ ≤ 0.30		2	Ignore	
	→ <u>x</u> ← ↓		$\Phi > 0.30$		0		
06	Y		Total		3		Minor
00	$\Phi = (x+y)/2$	6. 2 Line type(Non-display or	r displa	ny) :		Willion
	Line type	Dimension		Acceptance (Q'ty)			
	Line type	Length (L)	Width (W	V)	A area	B area	
		✓ [†] W		$W \le$	0.03	Ignore	
		L ≦5. 0	0.03 <w td="" ≤<=""><td>0.05</td><td>3</td><td>_</td><td></td></w>	0.05	3	_	
			W >	0.05	As round type	Ignore	
			Total		3		
		Dim	ension		Assentance	(O'tri)	
			ieter : Φ)		Acceptance A area	B area	
	Polarizer Bubble		$\Phi \leq 0.20$		gnore		
07		0.20 <	$\Phi \leq 0.50$		3	_	Minor
			$\Phi > 0.50$		0	Ignore	
		Т	otal		3		



◆Specification For TFT-LCD Module Less Than 3.5":

NO	Item		Criterion		Level
	Item The crack of glass	Symbols: X: The len Z: The thi t: The thi 8.1 Genera	Criterion gth of crack ickness of crack	Y: The width of crack. W: terminal length a: LCD side length ack between panels: Y SP [NG]	Level
		X	Seal width Z	z	
		≦ a	Crack can't enter viewing area	≦1/2 t	
		≦ a	Crack can't exceed the half of SP width.	1/2 t < Z ≤2 t	



◆Specification For TFT-LCD Module Less Than 3.5″:

Item	Criterion	Level
	Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 8. 1. 2 Corner crack:	
	X Y Z $\leq 1/5$ a Crack can't enter viewing area $Z \leq 1/2$ t	
	$\leq 1/5$ a Crack can't exceed the half of SP width. $1/2$ t $<$ Z ≤ 2 t	Minor
	8.2 Protrusion over terminal: 8.2.1 Chip on electrode pad: X X W Y X W Y X Y X Y X Y X Y Y X Y Y	
	$\begin{array}{c ccccc} X & Y & Z \\ \hline Front & \leq a & \leq 1/2 W & \leq t \\ \hline Back & \leq a & \leq W & \leq 1/2 t \\ \hline \end{array}$	
	The crack of glass	Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 8. 1. 2 Corner crack: X Y Z ≤1/5 a Crack can't enter viewing area ≤1/5 a Crack can't exceed the half of SP width. Crack can't exceed the half of SP width. 8. 2. 1 Chip on electrode pad: X Y Z X Y Z ✓ X



igstyle Specification For TFT-LCD Module Less Than 3.5":

Symbols: X: The length of crack Y: The width of crack. Z: The thickness of crack W: terminal length t: The thickness of glass a: LCD side length 8. 2. 2 Non-conductive portion:	NO	Item			
The crack of glass X		The crack of	Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 8. 2. 2 Non-conductive portion: X: The width of crack. W: terminal length a: LCD side length 8. 2. 2 Non-conductive portion: X: Y: The width of crack. W: terminal length a: LCD side length X: Y: The width of crack. W: terminal length a: LCD side length X: Y: The width of crack. W: terminal length a: LCD side length X: Y: The width of crack. W: terminal length a: LCD side length X: Y: The width of crack. W: terminal length a: LCD side length a: LCD side length a: LCD side length X: The width of crack. W: terminal length a: LCD side length a	Level	



\spadesuit Specification For TFT-LCD Module Less Than 3. 5" :

NO	Item	Criterion	Level
	Backlight elements	9. 1 Backlight can't work normally.	Major
09		9. 2 Backlight doesn't light or color is wrong.	Major
		9. 3 Illumination source flickers when lit.	Major
	General appearance	10. 1 Pin type \quantity \quantity \dimension must match type in structure diagram.	Major
		10. 2 No short circuits in components on PCB or FPC .	Major
10		10. 3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
10		10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10. 5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC) is ≤1.5 mm.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

	Hondbinty Tool oo	(101.501)			
NO.	TEST ITEM	TEST C	ONDITION		
1	High Temperature	Keep in +80°C ±2°C 240hrs			
	Storage Test	Surrounding temperature, then storage at normal condition 4hrs.			
2	Low Temperature	Keep in -30 $^{\circ}$ ±2 $^{\circ}$ 240hrs			
	Storage Test	Surrounding temperature, then st	- C		
	High Temperature /	Keep in +60 °C / 90 % R.H duration for 240hrs			
3	High Humidity	Surrounding temperature, then storage at normal condition 4hrs.			
	Storage Test	(Excluding the polarizer)	1000		
			→ +80°C → +25°C		
4	Temperature Cycling	(30mins) (5mins)			
	Storage Test	10	Cycle		
		Surrounding temperature, then st	orage at normal condition 4hrs.		
		Air Discharge:	Contact Discharge:		
		Apply 2 KV with 5 times	Apply 250 V with 5 times		
		Discharge for each polarity +/-	discharge for each polarity +/-		
	ESD Test	1. Temperature ambiance : 15℃	~35℃		
5		2. Humidity relative: 30%~60%			
J 3		3. Energy Storage Capacitance(Cs+Cd): 150pF±10%		
		4. Discharge Resistance(Rd): 330 Ω±10%			
		5. Discharge, mode of operation			
			successive discharges at least 1 sec)		
		(Tolerance if the output voltage in	dication: ±5%)		
	Vibration Test	1. Sine wave 10∼55 Hz frequen	cy (1 min/sweep)		
6	(Packaged)	2. The amplitude of vibration :1.	5 mm		
	(Tuenugeu)	3. Each direction (X \ Y \ Z) du	ration for 2 Hrs		
		Packing Weight (Kg	Drop Height (cm)		
		0 ~ 45.4	122		
	Drop Test	45.4 ~ 90.8	76		
7	(Packaged)	90.8 ~ 454	61		
		Over 454	46		
		Drop Direction: **1 corner / 3 ed	ges / 6 sides each 1time		
		<u> </u>			



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

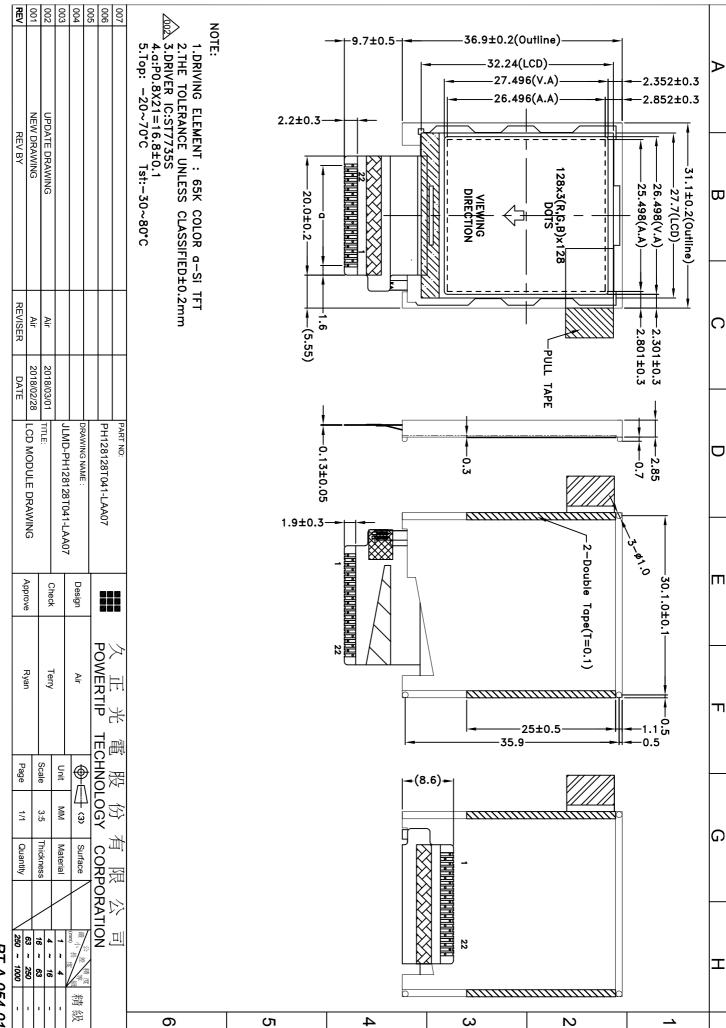
- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM
- 5.2.10 Caution!(LCM products with Capacitive Touch Panel)
 Strong EMI-sources such as switch-mode power supplies (SMPS) can lead to touch malfunction (e.g. ghost-touches).
 - Therefore, the touch needs to be thoroughly tested inside the target application.

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25° C \pm 5° C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility
 - This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



PT-A-054-01

Approve Check Contact LCM包裝規格書 Ver.001 LCM Packaging Specifications Documents NO. | JPKG-PH128128T041-LAA07 Ryan Terry Air (For Tray) 1.包裝材料規格表 (Packaging Material): (per carton) Item 1Pcs Weight Total Weight No. Dimensions (mm) Quantity 成品 (LCM) PH128128T041-LAA07 31.1 X 36.9 X 2.85 1440 1 0.0045 6.48 2 多層薄膜(1)POF 19"X350X0.015 6 OTFILM0BA03ABA 3 352 X 260 X 10.8 TRAY 盤 (2)Tray TY0000000068 54 0.096 5.184 内盒(3)Product Box 4 BX36627063ABBA 393 X 274 X 68 0.2692 6 1.6152 OTPLB00PL08ABA 2 5 550 X 393 X 20 0.0284 0.0568 保利龍板(4)Polylon board 6 外紙箱(5)Carton BX57041027CCBA 570 X 410 X 265 1.4208 1 1.4208 7 8 9 2. 一整箱總重量 (Total LCD Weight in carton): 14.76 Kg±10% 3.單箱數量規格表 (Packaging Specifications and Quantity): (1)LCM quantity per box : no per tray x no of tray 8 30 240 (2) Total LCM quantity in carton: quantity per box x no of boxes 240 6 1440 (4)保利龍板 Polylon board Use empty tray 空盤 (1)多層薄膜 POF Put products into the tray (2)TRAY 盤 (4)保利龍板 Tray Polylon board (3)内盒 Tray stacking Product Box (5)外紙箱 Carton 特 記 事 項 (REMARK) Detail B

Trav 1





ALL TECHNOLOGIES. ALL COMPETENCIES. ONE SPECIALIST.



DATA MODUL AG Landsberger Straße 322 DE-80687 Munich Phone: +49-89-56017-0 DATA MODUL WEIKERSHEIM GMBH Lindenstraße 8 DE-97990 Weikersheim Phone: +49-7934-101-0



More information and worldwide locations can be found at